Materials List for:
Origami Inspired Self-assembly of Patterned and Reconfigurable Particles

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<table>
<thead>
<tr>
<th>Name</th>
<th>Company</th>
<th>Catalog Number</th>
<th>Comments</th>
</tr>
</thead>
<tbody>
<tr>
<td>950 Poly methyl methacrylate A11</td>
<td>Micro Chem</td>
<td>M230011</td>
<td>Sacrificial layer</td>
</tr>
<tr>
<td>Chromium-plated tungsten rods</td>
<td>R. D. Mathis Company</td>
<td>CRW-2</td>
<td>Evaporation source for Cr</td>
</tr>
<tr>
<td>Copper slug</td>
<td>Alfa Aesar</td>
<td>7440-50-8</td>
<td>Evaporation source for Cu</td>
</tr>
<tr>
<td>Gold slug</td>
<td>Alfa Aesar</td>
<td>7440-57-5</td>
<td>Evaporation source for Au</td>
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<tr>
<td>SPR 220 7.0</td>
<td>Rohm and Haas</td>
<td>10016640</td>
<td>Positive photoresist</td>
</tr>
<tr>
<td>S 1800 series photoresists</td>
<td>Rohm and Haas</td>
<td>10016574</td>
<td>Positive photoresist</td>
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<tr>
<td>Megaposit MF- 26 A developer</td>
<td>Rohm and Haas</td>
<td>10016574</td>
<td>Developer for SPR 220 7.0 photoresist</td>
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<tr>
<td>Microposit 351 developer</td>
<td>Rohm and Haas</td>
<td>10016653</td>
<td>Developer for S 1800 series photoresists</td>
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<tr>
<td>Nickel Sulfamate</td>
<td>Technic Inc.</td>
<td>030175</td>
<td>Plating solution for Ni</td>
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<tr>
<td>Techni Solder Mate NF 820 60/40</td>
<td>Technic Inc.</td>
<td>330681</td>
<td>Plating solution for Pb-Sn hinges</td>
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<tr>
<td>RTU</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>APS 100 Copper etchant</td>
<td>Transene Company Inc.</td>
<td>021221</td>
<td>Copper etchant</td>
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<tr>
<td>CRE 473 Chromium etchant</td>
<td>Transene Company Inc.</td>
<td>040901</td>
<td>Chromium etchant</td>
</tr>
<tr>
<td>1-Methyl-2-Pyrollidinone (NMP)</td>
<td>Sigma-Aldrich</td>
<td>M79603</td>
<td>High boiling point organic solvent for Pb-Sn hinge based self-folding</td>
</tr>
<tr>
<td>Indalloy 5RMA flux</td>
<td>Indium Corporation of America</td>
<td>FL28372</td>
<td>Chemical that cleans the solder surface and inhibits oxidation for good Pb-Sn reflow</td>
</tr>
</tbody>
</table>